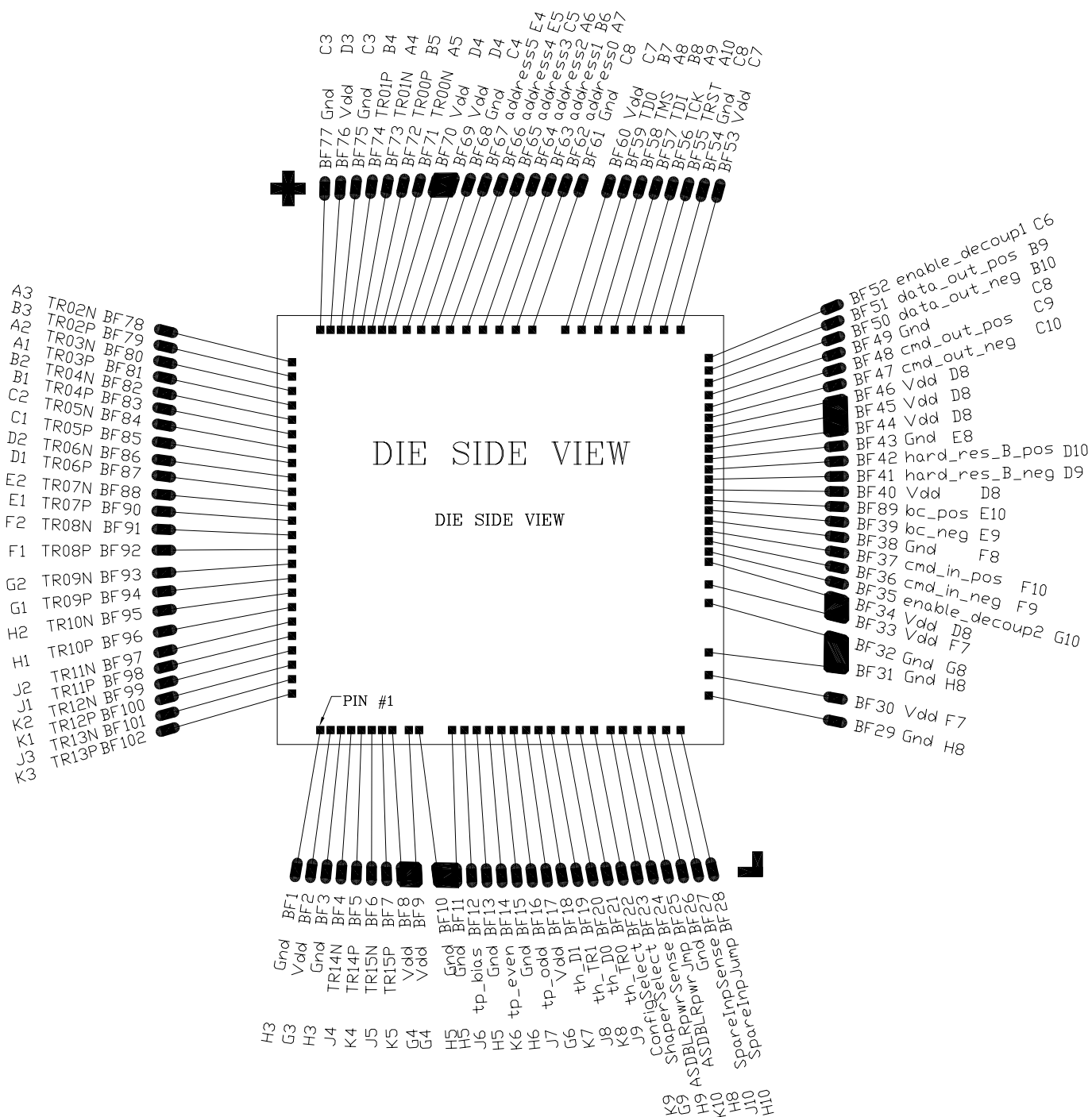




Signetics Korea

TITLE:

FBGA 11X13MM 100BALL
0.8MM PITCH, 2 LAYER,
BONDING DIAGRAM
(DTMROC-S)

NOTE:

GND NET CONNECTED TO FOLLOW BALLS :
C3,C4,C8,D5,D7,E3,E8,F5,F8,G5,G7,G8,H3,H4,H5,H6,
H7,H8

VDD NET CONNECTED TO FOLLOW BALLS :
C7,D3,D4,D6,D8,E6,E7,F3,F4,F6,F7,G3,G4,G6

A1 — A10
| TOP
| VIEW
|
K1 — K10

SUB-TITLE:		CUSTOMER: Upenn	DIE PAD SIZE: 7.7X7.8MM		
FILE NAME: BLB-11132		DEVICE: DTMROC-S	DIE SIZE W/ SEAL RING & SCRIBE LINE: 5.42X5.21MM		
FRAME DWG#: EEV-FLB11132		CUSTOMER BD#:	DIE SIZE W/O SEAL RING & SCRIBE LINE: 5.2X5.0MM		
DETAIL DWG#: EEV-FLB11132		SIG. BD#:	BOND PAD SIZE/PITCH: 100SQ UM/MIN125UM		
FRAME STOCK#: TBD		PART #:	WIRE DIAMETER: 1.0MIL		
SCALE: 8:1	SHEET: 1 OF 1	FRAME CODE: TBD	LONGEST/SHORTEST WIRE LENGTH: 73MIL/61MIL		
DATE	REV.	DESCRIPTION	DRAWN	CHECKED	APPROVED
10/23/'02	-	GENERATION	MJ BAIK	DS SEO	